



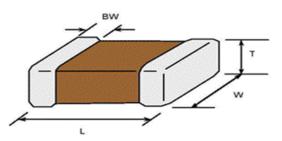
## **SPECIFICATION**

(Reference sheet)

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : • Description :
- CL05C1R8CB5NNNC CAP, 1.8pF, 50V, ±0.25pF, C0G, 0402
- A. Samsung Part Number

		<u>CL</u> ①	<u>05</u> ②	<u>С</u> З	<u>1R8</u> ④	<u>C</u> 5	<u>В</u> 6	<u>5</u> 7	<u>N</u> 8	<u>N</u> 9	<u>N</u> 10	<mark>C</mark> 100
1	Series	Samsung Multi-layer Ceramic Capacitor										
2	Size	0402 (inch	code)		L:	1.00	± 0.0	5	mm		W:	0.50 ± 0.05 mm
3	Dielectric	C0G				8	Inner	elec	trode			Ni
4	Capacitance	<b>1.8</b> pF					Term	inatio	on			Cu
5	Capacitance	<b>±0.25</b> pF					Platin	ng				Sn 100% (Pb Free)
	tolerance					9	Prod	uct				Normal
6	Rated Voltage	50 V				10	Spec	ial				Reserved for future use
$\bigcirc$	Thickness	0.50 ± 0.0	5 mm			1	Pack	aging	J			Cardboard Type, 7" reel

## **B.** Structure and dimension



Samsung P/N	Dimension(mm)								
(Lead Free)	L	W	Т	BW					
CL05C1R8CB5NNNC	1.00±0.05	0.50±0.05	0.50±0.05	0.25±0.10					

## C. Samsung Reliability Test and Judgement condition

	Performance	Test condition					
Capacitance Within specified tolerance		1Mt±10% 0.5~5Vrms					
<b>Q</b> 436 min							
Insulation	10,000Mohm or 500Mohm <i>µ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	C0G						
Characteristics	(From -55 $^{\circ}$ to 125 $^{\circ}$ , Capacitance change should be within ±30PPM/ $^{\circ}$ )						
Adhesive Strength No peeling shall be occur on the		500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	within $\pm 2.5\%$ or $\pm 0.25pF$ whichever is larger						
	Tan δ, IR : initial spec.						
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours $\times$ 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within $\pm 7.5\%$ or $\pm 0.75$ pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 106 min						
	IR : 500Mohm or 25Mohm $\cdot \mu F$						
	Whichever is smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within $\pm 3\%$ or $\pm 0.3 \text{ pF}$ whichever is larger	Max. operating temperature					
	Q : 218 min	1000+48/-0hrs					
	IR : 1,000Mohm or 50Mohm · μF						
	Whichever is smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger	Min. operating temperature $\rightarrow$ 25 °C					
	Tan δ, IR : initial spec.	$\rightarrow$ Max. operating temperature $\rightarrow$ 25 °C					
		5 cycle test					
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\* The reliability test condition can be replaced by the corresponding accelerated test condition.

## D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max )

A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.